Schottky Power Rectifier

Surface Mount Power Package

Schottky Power Rectifiers employ the use of the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes, in surface mount applications where compact size and weight are critical to the system. These state-of-the-art devices have the following features:

Features

- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- High Blocking Voltage 100 V
- 150°C Operating Junction Temperature
- Guardring for Stress Protection
- This is a Pb-Free Device

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped in 12 mm Tape and Reel, 5000 Units per Reel
- Cathode Polarity Band

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V
Average Rectified Forward Current $T_L = 130^{\circ}C$	I _{F(AV)}	1.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	50	A
Operating Junction Temperature (Note 1)	TJ	-65 to +150	°C
Voltage Rate of Change	dv/dt	10	V/ns

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.



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SCHOTTKY BARRIER RECTIFIER 1.0 AMPERE 100 VOLTS



SMA-FL CASE 403AA PLASTIC STYLE 6

MARKING DIAGRAM



RAD = Device Code

= Assembly Location

Y = Year

WW = Work Week

= Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2) Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ hetaJL} \ R_{ hetaJA}$	25 90	°C/W

^{2. 1} inch square pad size (1×0.5) inch) for each lead on FR4 board.

ELECTRICAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 4) (i _F = 1.0 A, T _J = 25°C)	V _F	0.75	V
Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, T_J = 25°C) (Rated dc Voltage, T_J = 100°C)	I _R	0.5 5.0	mA

^{3. 1} inch square pad size (1 \times 0.5 inch) for each lead on FR4 board.

ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
MBRAF1100T3G	RAD	SMA-FL (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

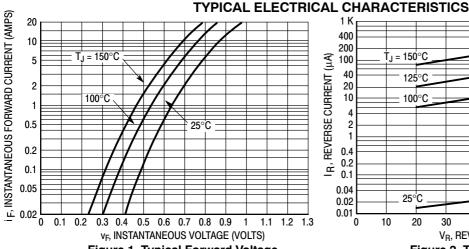


Figure 1. Typical Forward Voltage

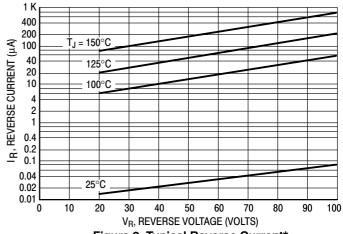


Figure 2. Typical Reverse Current*

^{*}The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if $V_{\rm R}$ is sufficient below rated $V_{\rm R}$.

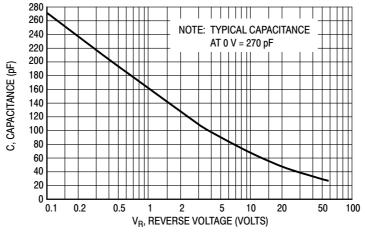


Figure 3. Typical Capacitance

^{4.} Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

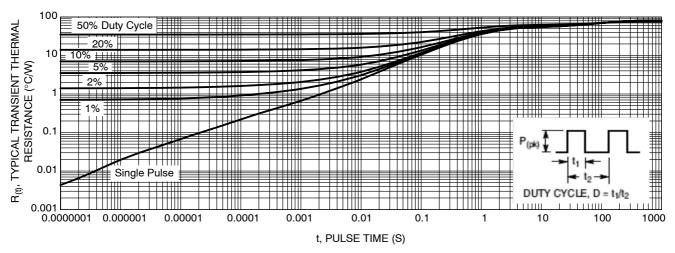
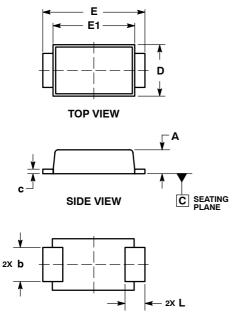


Figure 4. Typical Transient Thermal Response, Junction-to-Ambient

PACKAGE DIMENSIONS

SMA-FL CASE 403AA-01 ISSUE O



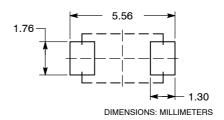
BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS

_	00111110221110 21111			
		MILLIMETERS		
Ш	DIM	MIN	MAX	
	Α	0.90	1.10	
	b	1.25	1.65	
	С	0.15	0.30	
L	D	2.40	2.80	
	Е	4.80	5.40	
	E1	4.00	4.60	
Г	L	0.70	1.10	

RECOMMENDED SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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